





20V COMPLEMENTARY MEDIUM POWER TRANSISTOR IN SOT26

Features

- NPN + PNP combination
- $BV_{CEO} > 20 (-20)V$
- $BV_{EBO} > 7 (-7)V$
- Continuous Collector Current I_C = 4 (-3.5)A
- V_{CE(sat)} < 50 (-65)mV @ 1A
- $R_{CE(sat)} = 35 (54) m\Omega$
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description

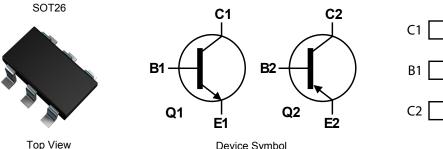
Advanced process capability has been used to achieve this high performance device. Combining NPN and PNP transistors in the SOT26 package provides a compact solution for the intended applications.

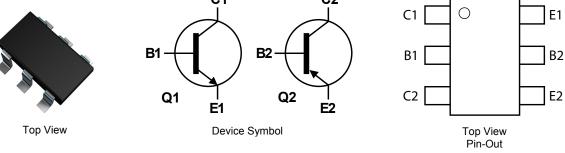
Mechanical Data

- Case: SOT26
- Case Material: molded plastic, "Green" molding compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.015 grams (approximate)

Applications

- MOSFET and IGBT gate driving
- Motor drive





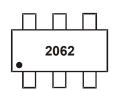
Ordering Information (Note 4)

Ī	Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	ZXTC2062E6TA	2062	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/ for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com

Marking Information



2062 = Product Type Marking Code



Maximum Ratings - Q1 (NPN Transistor) (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	100	V
Collector-Emitter Voltage	V _{CEO}	20	V
Emitter-Collector Voltage (reverse blocking)	V _{ECO}	5	V
Emitter-Base Voltage	V _{EBO}	7	V
Continuous Collector Current	Ic	4	Α
Peak Pulsed Collector Current	I _{CM}	10	Α
Base Current	I _B	1	A

Maximum Ratings – Q2 (PNP Transistor) (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-25	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Collector Voltage (reverse blocking)	V _{ECO}	-4	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	Ic	-3.5	Α
Peak Pulsed Collector Current	I _{CM}	-10	Α
Base Current	I _B	-1	A

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

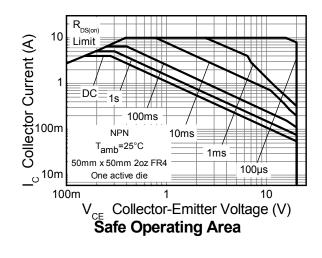
Characteristic	Symbol	Value	Unit		
	(Notes 5 & 9)		0.7 5.6		
	(Notes 6 & 9)	P _D	0.9 7.2	W mW/°C	
Power Dissipation Linear Derating Factor	(Notes 6 & 10)		1.1 8.8		
	(Notes 7 & 9)		1.1 8.8		
	(Notes 8 & 9)		1.7 13.6		
	(Notes 5 & 9) (Notes 6 & 9)		179 139		
Thermal Resistance, Junction to Ambient	(Notes 6 & 10)	$R_{ hetaJA}$	113		
	(Notes 7 & 9) (Notes 8 & 9)		113 73	°C/W	
Thermal Resistance, Junction to Lead	(Note 11)	$R_{ heta JL}$	87.58		
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C		

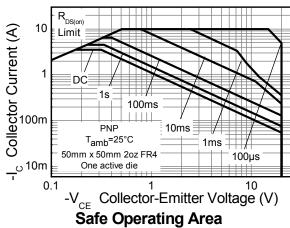
Notes:

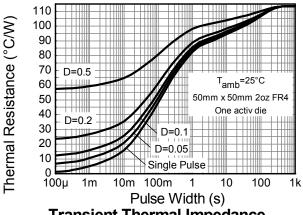
- 5. For a device surface mounted on 15mm x 15mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
- Same as note (5), except the device is surface mounted on 25mm x 25mm 1oz copper.
 Same as note (5), except the device is surface mounted on 50mm x 50mm 2oz copper.
- 8. Same as note (7), except the device is measured at t < 5 seconds.
- 9. For device with one active die, both collectors attached to a common heatsink.
- 10. For device with two active dice running at equal power, split heatsink 50% to each collector.
- 11. Thermal resistance from junction to solder-point (at the end of the collector lead).

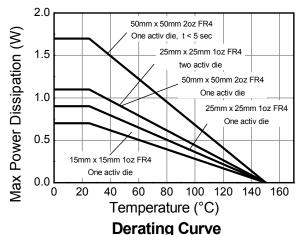


Thermal Characteristics and Derating Information

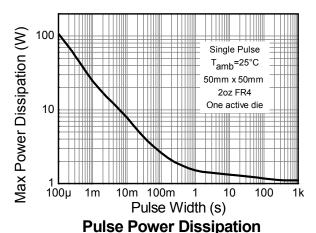








Transient Thermal Impedance





Electrical Characteristics - Q1 (NPN Transistor) (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Collector-Base Breakdown Voltage	BV _{CBO}	100	140	_	V	$I_C = 100 \mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	20	35	_	V	$I_C = 10 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.3	_	V	$I_E = 100 \mu A, I_C = 0$	
Emitter-Collector breakdown voltage (base open)	BV _{ECO}	5	6	_	V	I _E = 100μA	
Collector Cutoff Current	I _{CBO}	_	<1	50 0.5	nA μA	V _{CB} = 100V V _{CB} = 100V, T _A = +100°C	
Collector Cutoff Current	I _{EBO}		<1	50	nA	V _{EB} = 5.6V	
ON CHARACTERISTICS (Note 12)	250			I	I		
DC Current Gain	h _{FE}	300 280 140	450 420 210 15	900 — — —	_	I _C = 10mA, V _{CE} = 2V I _C = 1A, V _{CE} = 2V I _C = 4A, V _{CE} = 2V I _C = 15A, V _{CE} = 2V	
Collector-Emitter Saturation Voltage	V _{CE(sat)}	_	40 60 95 140	50 75 115 190	mV	I _C = 1.0A, I _B = 100mA I _C = 1.0A, I _B = 20mA I _C = 2.0A, I _B = 40mA I _C = 4A, I _B = 200mA	
Base-Emitter Saturation Voltage	V _{BE(sat)}	_	940	1050	mV	I _C = 4A, I _B = 200mA	
Base-Emitter Turn-On Voltage	V _{BE(on)}	_	810	900	mV	I _C = 4A, V _{CE} = 2V	
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	C _{obo}		17	25	pF	V _{CB} = 10V, f = 1.0MHz	
Current Gain-Bandwidth Product	f⊤		215	_	MHz	V _{CE} = 10V, I _C = 50mA, f = 100MHz	
Delay Time	t _d	_	68	_	ns		
Rise Time	t _r	_	72	_	ns	\\ -40\\ -40\	
Storage Time	ts		361	_	ns	$V_{CC} = 10V$, $I_C = 1A$, $I_{B1} = -I_{B2} = 10mA$	
Fall Time	t _f		64	_	ns		

Notes: 12. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



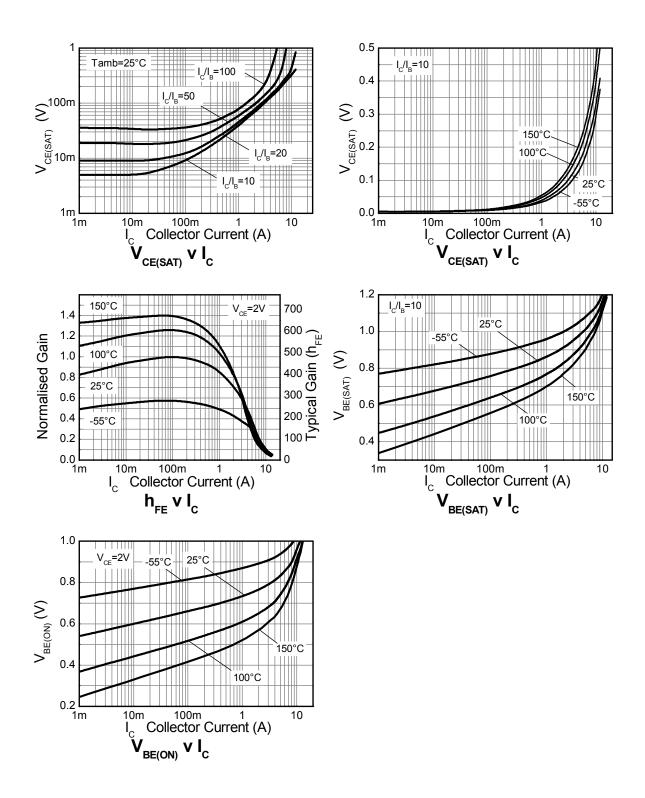
Electrical Characteristics – Q2 (PNP Transistor) (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_CBO	-25	-55	_	V	$I_C = -100 \mu A, I_E = 0$
Collector-Emitter Breakdown Voltage (Note 12)	BV_{CEO}	-20	-45		V	$I_{\rm C} = -10 \rm mA, \ I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	-7	-8.3		V	$I_E = -100 \mu A, I_C = 0$
Collector Cutoff Current	1	_	< -1	-50	nA	V _{CB} = -25V
Collector Cuton Current	I _{CBO}	_		-0.5	μΑ	$V_{CB} = -25V, T_A = +100^{\circ}C$
Collector Cutoff Current	I _{EBO}		< -1	-50	nA	V _{EB} = -5.6V
ON CHARACTERISTICS (Note 12)						
		300	450	900		$I_C = -10 \text{mA}, V_{CE} = -2 \text{V}$
DC Current Gain	h _{FE}	170	300	_		$I_C = -1.0A$, $V_{CE} = -2V$
Do danoni dani	IIFE.	65	100	_		$I_C = -3.5A, V_{CE} = -2V$
			15			$I_C = -10A$, $V_{CE} = -2V$
			-55	-65	m\/	$I_C = -1.0A$, $I_B = -100mA$
Collector-Emitter Saturation Voltage	V _{CE(sat)}		-100	-135		$I_C = -1.0A$, $I_B = -20mA$
Concotor Emilior Cataration Voltage	▼ CE(Sat)	_	-185	-280		$I_C = -2.0A$, $I_B = -40mA$
			-190	-250		$I_C = -3.5A$, $I_B = -175mA$
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	_	-925	-1000	mV	$I_C = -3.5A$, $I_B = -175mA$
Base-Emitter Turn-On Voltage	$V_{BE(on)}$	_	-835	-900	mV	$I_C = -3.5A$, $V_{CE} = -2V$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_{obo}		21	30	pF	$V_{CB} = -10V, f = 1.0MHz$
Current Gain-Bandwidth Product	f_{T}		290		MHz	$V_{CE} = -10V, I_{C} = -50mA, f = 100MHz$
Delay Time	t_d		56		ns	
Rise Time	t _r		68		ns	$V_{CC} = -10V, I_{C} = -1A,$
Storage Time	ts	_	158		ns	$I_{B1} = -I_{B2} = -10 \text{mA}$
Fall Time	t _f		59		ns	

Notes: 12. Measured under pulsed conditions. Pulse width $\leq 300 \mu s$. Duty cycle $\leq 2\%$.

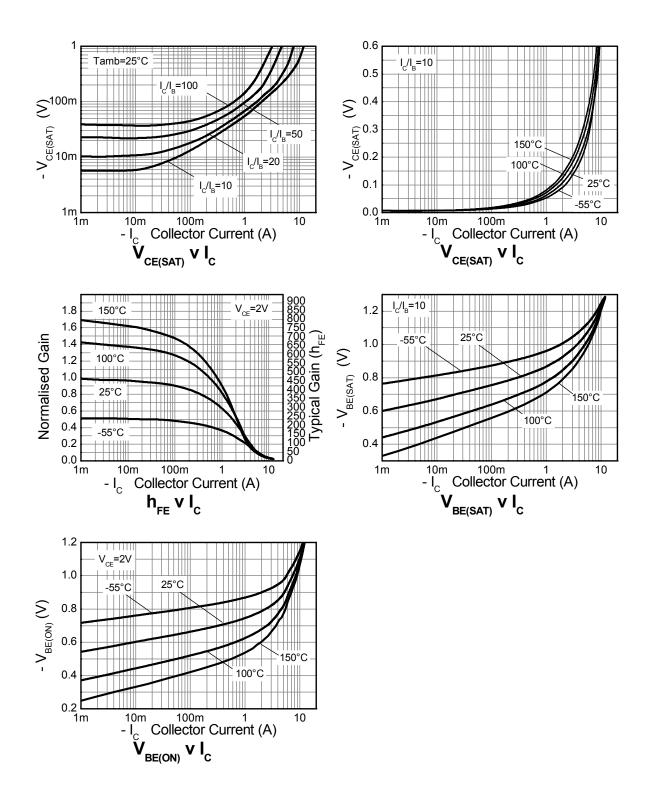


Typical Electrical Characteristics – Q1 (NPN Transistor) (@TA = +25°C, unless otherwise specified.)





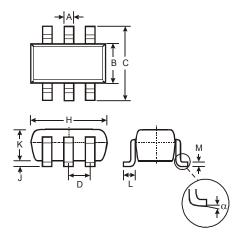
Typical Electrical Characteristics – Q2 (PNP Transistor) (@TA = +25°C, unless otherwise specified.)





Package Outline Dimensions

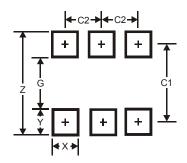
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT26							
Dim	Min	Max	Тур				
Α	0.35	0.50	0.38				
В	1.50	1.70	1.60				
С	2.70	3.00	2.80				
D	_		0.95				
Н	2.90	3.10	3.00				
J	0.013	0.10	0.05				
K	1.00	1.30	1.10				
L	0.35	0.55	0.40				
M	0.10	0.20	0.15				
α	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95





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